

CORRECTION

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Cite this: *J. Mater. Chem. C*, 2023,  
11, 15774

DOI: 10.1039/d3tc90239k

rsc.li/materials-c

## Correction: Copper particle-free ink with enhanced performance for inkjet-printed flexible UWB antennas

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Correction for 'Copper particle-free ink with enhanced performance for inkjet-printed flexible UWB antennas' by Wendong Yang et al., *J. Mater. Chem. C*, 2023, **11**, 14429–14438, <https://doi.org/10.1039/D3TC02515B>.

The authors regret an error in Fig. 4 of the published article, where Fig. 4a was unfortunately replaced with a duplicate of Fig. 4b. The corrected version of Fig. 4 is shown here (the caption remains unchanged).

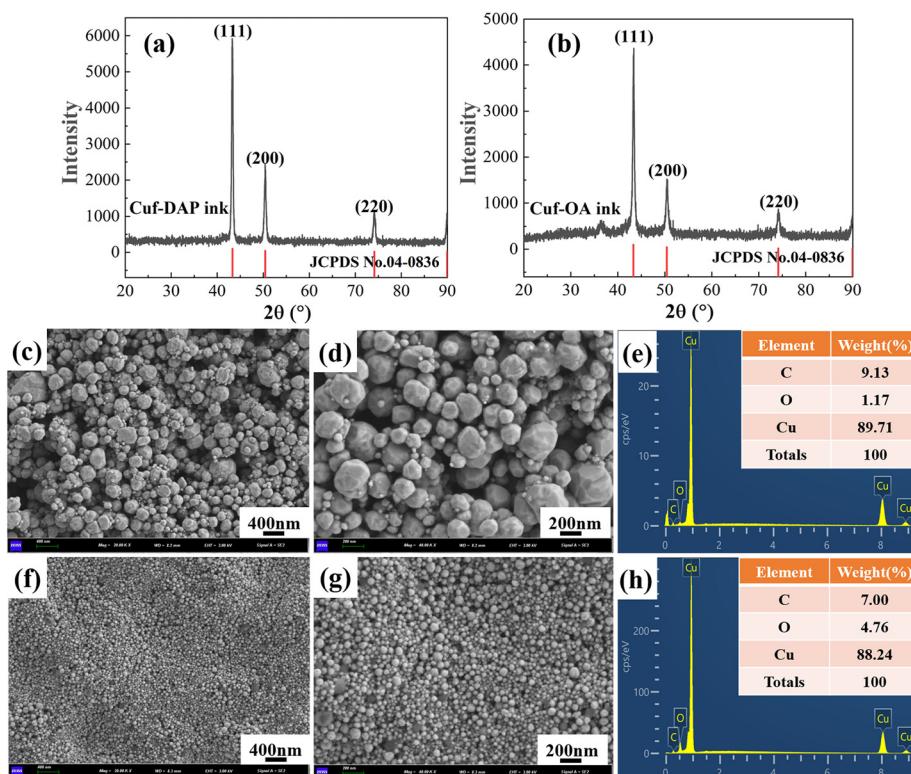


Fig. 4 XRD, surface morphologies and EDS results of the produced copper films from (a) and (c)–(e) Cuf-DAP ink and (b) and (f)–(h) Cuf-OA ink sintered at 170 °C for 60 minutes.

The Royal Society of Chemistry apologises for these errors and any consequent inconvenience to authors and readers.

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